



BSI Standards Publication

Thermal standardization on semiconductor packages

Part 3: Thermal circuit simulation models of discrete semiconductor packages for transient analysis

National foreword

This British Standard is the UK implementation of EN IEC 63378-3:2025. It is identical to IEC 63378-3:2025.

The UK participation in its preparation was entrusted to Technical Committee EPL/47, Semiconductors.

A list of organizations represented on this committee can be obtained on request to its committee manager.

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